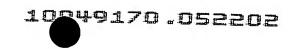
MAT-8211US



VERSION WITH MARKINGS SHOWING CHANGES MADE

Please replace claims 3, 6, 9, 10, 13, 14, and 17-19 with the following amended claims:

- 3. (Amended) The method of claim 1-or-2, further comprising the steps of: forming a via-conductor through forming a through-hole in the un-sintered green sheet; and connecting the conductive pattern to the via conductor.
- 6. (Amended) The method of claim 4-or-5, further comprising the steps of:

 forming a via-conductor through forming a through-hole in the un-sintered green sheet;
 and

 connecting the conductive pattern to the via-conductor.
- 9. (Amended) The method of claim 7-or-8, further comprising the steps of:

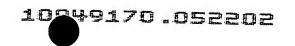
 forming a via-conductor through forming a through-hole in the un-sintered green sheet;
 and

 connecting the conductive patterns to the via-conductor.
- 10. (Amended) The method of any one of claims claim 7-to 9, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered substrate; and connecting the conductive pattern to the via-conductor.

13. (Amended) The method of claim 11-or-12, further comprising the step of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;
and



connecting the conductive patterns to the via-hole conductor.

14. (Amended) The method of any one of claim claims 11-to 13, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting the conductive pattern to the via-conductor.

- 17. (Amended) The method of claim 15-or-16, wherein the first intaglio and the second intaglio are identical to each other.
- 18. (Amended) The method of any one of claims claim 15-to 17, further comprising the steps of:

forming a first via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting at least one of the first and second conductive patterns to the first viaconductor.

19. (Amended) The method of any one of claims claim 15 to 18, further comprising the steps of:

forming a second via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting at least one of said first and second conductive patterns to the second viaconductor.